



**EV Group unlocks agile and efficient production scaling with next-gen nanoimprint lithography system – June 8, 2021**



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### Top Stories

#### Automating mask SEM analysis using digital twins

Deep Learning can learn features from the SEM images generated using digital twins, then use that learning to find defects on real SEM images. [More>>](#)



### GlobalFoundries and GlobalWafers partnering to expand semiconductor wafer supply

GLOBALFOUNDRIES and GlobalWafers Co., Ltd. (GWC), one of the top silicon wafer manufacturers in the world, today announced an \$800 million agreement to add 300mm silicon-on-insulator (SOI) wafer manufacturing and expand existing 200mm SOI wafer production at GWC's MEMC facility in O'Fallon, Missouri. [More>>](#)



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### Tech News

### Atom swapping could lead to ultra-bright, flexible next-generation LEDs

An international group of researchers has developed a new technique that could be used to make more efficient low-cost light-emitting materials which are flexible and can be printed using ink-jet techniques. [More>>](#)



### A quantum step to a heat switch with no moving parts

Researchers have discovered a new electronic property at the frontier between the thermal and

quantum sciences in a specially engineered metal alloy – and in the process identified a promising material for future devices that could turn heat on and off with the application of a magnetic “switch.” [More>>](#)



### EV Group unlocks agile and efficient production scaling with next-gen nanoimprint lithography system

EV Group (EVG), a supplier of wafer bonding and lithography equipment for the MEMS, nanotechnology, and semiconductor markets, today announced the EVG770 NT — its next-generation step-and-repeat nanoimprint lithography (NIL) system. [More>>](#)



### INSIGHTS INTO FAILURE ANALYSIS AND MATERIAL TESTING – FAMT 2021

International SPM Symposium on Failure Analysis and Material Testing — FAMT 2021 will be virtually hosted by Fraunhofer Institute for Microstructure of Materials and Systems IMWS and Park Systems on July 1. Join online and discuss the latest application studies from the electronic industry and innovative test methods and tools for physical failure analysis of the future! [Learn more.](#)

Business News

SIA welcomes White House report on strengthening America’s semiconductor supply chains

The Semiconductor Industry Association welcomed the release of a White House report on strengthening the supply chains of critical products, including semiconductors. [More>>](#)



### **Alpha and Omega Semiconductor announces new director nominees**

Alpha and Omega Semiconductor Limited, today announced that its Board of Directors, upon recommendation by the Nominating and Corporate Governance Committee, intends to nominate Hanqing (Helen) Li and So-Yeon Jeong as directors to be elected at its 2021 Annual General Meeting of Shareholders. [More>>](#)



### **Featured Product**

**[InSight CAP Automated AFM Metrology](#)** - Specifically designed for semiconductor CMP and etch metrology, InSight Cap's flexible configurations support wafer sizes from 100 to 300mm, enabling precision measurements for a wide range of end applications. From highly productive labs to fully automated fabs, the InSight CAP profiler can be optimally configured for the most cost-effective metrology solution. [Learn more.](#)

**Delphon Helps Transform Ideas into New Products**



Delphon is the materials incubator and advanced manufacturing center known for solving complex product development and manufacturing challenges by supporting innovation at its Gel-Pak, UltraTape and TouchMark divisions. Learn more about how we can help transform your ideas into new products.

The image shows the cover of the "SEMICONDUCTOR DIGEST" magazine on the left. The cover features a photograph of a person in a cleanroom environment wearing a white protective suit and a red cap. The main headline on the cover is "Mitigation of Pattern Collapse IN EUV LITHOGRAPHY". To the right of the magazine cover, the text "SEMICONDUCTOR DIGEST" is displayed in a large, bold, blue font, with "DIGEST" in white text inside a red rectangular box. Below this, the text "Read the April/May issue. All articles are exclusive to the magazine!" is written in a bold, dark blue font. At the bottom right, there is a red button with the text "CLICK HERE" in white.

[Webcasts and Technology Papers](#)

**Determination of Impurities in Electronic-Grade Hydrochloric Acid with NexION 5000  
ICP-MS**

[View Paper](#)

**High Reliability Semiconductor Devices: The Engine of Modern Automotive Capability**

[View Paper](#)

**Cathodoluminescence as a technique for inspection, metrology, and failure analysis of  
microLED processing**

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**Guided Analytics for Materials Innovation —  
Semiconductor Applications**

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**A New Differential Pressure Sensor Based MFC for  
Advanced Semiconductor Processing**

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**No Safety, No Security Webcast**

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**Web Editor**

Shannon Davis

603-547-5309

[sdavis@semiconductordigest.com](mailto:sdavis@semiconductordigest.com)

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